

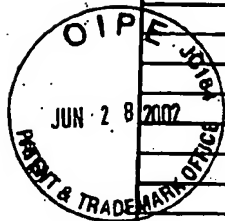
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U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub- class	Filing Date
	1	3,842,189	10/15/1974	Southgate	174	52	01/08/1973
	2	5,385,477	1/31/1995	Vaynkof et al.	439	66	07/30/1993
	3	5,476,211	12/9/1995	Khandros	228	180.5	11/16/1993
	4	5,532,612	6/12/1996	Liang	324	760	7/19/1994
	5	5,613,861	03/25/1997	Smith et al.	439	81	06/07/1995
	6	5,756,021	5/26/1998	Hedrick et al.	264	45.1	03/29/1996
	7	5,772,451	6/30/1998	Dozier II, et al.	439	70	10/18/1995
	8	5,772,451	6/30/1998	Dozier, II et al.	439	70	10/18/1995
	9	5,806,181	9/15/1998	Khandros et al.	29	874	1/24/1997
	10	5,820,014	10/13/1998	Dozier, II et al.	228	56.3	1/11/1996
	11	5,829,128	11/3/1998	Eldridge et al.	29	855	11/15/1995
	12	5,832,601	11/10/1998	Eldridge et al.	29	843	4/15/1997
	13	5,832,601	11/10/1998	Eldridge et al.	29	843	4/15/1997
	14	5,847,572	12/8/1998	Iwasaki et al.	324	755	1/3/1997
	15	5,852,871	12/29/1998	Khandros	29	843	12/11/1995
	16	5,854,946	2/2/1999	Eldridge et al.	29	843	4/15/1997
	17	5,864,946	2/2/1999	Eldridge et al.	29	843	4/15/1997
	18	5,878,486	3/9/1999	Eldridge et al.	29	840	4/15/1997
	19	5,884,398	3/23/1999	Eldridge et al.	29	843	4/15/1997
	20	5,884,398	3/23/1999	Eldridge et al.	29	843	4/15/1997
	21	5,897,326	4/27/1999	Eldridge et al.	438	14	4/15/1997
	22	5,912,046	6/15/1999	Eldridge et al.	427	126.2	5/9/1997
	23	5,917,707	6/29/1999	Khandros et al.	361	776	11/15/1994
	24	5,944,537	8/31/1999	Smith et al.	439	81	12/15/1997
	25	5,974,662	11/2/1999	Eldridge et al.	29	842	11/9/1995
	26	5,983,493	11/16/1999	Eldridge et al.	29	855	4/15/1997
	27	5,983,493	11/16/1999	Eldridge et al.	29	855	4/15/1997
	28	5,994,152	11/30/1999	Khandros et al.	436	617	1/24/1997
	29	5,994,152	11/30/1999	Khandros et al.	436	617	1/24/1997
	30	5,994,222	11/30/1999	Smith et al.	438	689	4/25/1997
	31	5,994,781	11/30/99	Smith	257	773	5/29/1998
	32	5,998,228	12/7/1999	Eldridge et al.	438	15	4/15/1997
	33	5,998,228	12/7/1999	Eldridge et al.	438	15	4/15/1997
	34	5,998,864	12/7/1999	Khandros et al.	257	723	5/27/1997
	35	6,001,671	12/14/1999	Fjelstad	438	112	4/18/1996
	36	6,002,168	12/14/1999	Bellaar et al.	257	696	11/25/1997
	37	6,007,349	12/28/1999	Distefano et al.	439	71	1/3/1997
	38	6,012,224	1/11/2000	DiStefano et al.	29	840	9/25/1997
	39	6,020,220	1/1/2000	Gilleo et al.	438	119	9/5/1996
	40	6,023,103	2/8/2000	Chang et al.	257	781	6/30/1998
	41	6,023,103	2/8/2000	Chang et al.	257	781	6/30/1998
	42	6,029,344	2/29/2000	Khandros et al.	29	874	8/12/1998
	43	6,029,344	2/29/2000	Khandros et al.	29	874	8/12/1998

10/069,902



44	6,030,856	2/29/2000	DiStefano et al.	438	117	6/10/1997
45	6,032,356	3/7/2000	Eldridge et al.	29	843	4/15/1997
46	6,033,935	3/7/2000	Dozier II, et al.	438	117	6/30/1998
47	6,042,712	3/28/2000	Mathieu	205	209	5/21/1998
48	6,043,563	3/28/2000	Eldridge et al.	257	784	10/20/1997
49	6,044,548	4/4/2000	Distefano et al.	29	840	3/10/1998
50	6,045,396	4/4/2000	Tighe	439	493	9/12/1997
51	6,045,655	4/4/2000	DiStefano et al.	156	324.4	10/13/1998
52	6,046,076	4/4/2000	Mitchell et al.	438	127	11/20/1997
53	6,049,972	4/18/2000	Link et al.	29	827	1/23/1998
54	6,049,976	4/18/2000	Khandros	29	843	6/1/1995
55	6,050,829	4/18/2000	Eldridge et al.	439	67	8/28/1997
56	6,050,829	4/18/2000	Eldridge et al.	439	67	8/28/1997
57	6,054,337	4/25/2000	Solberg	438	107	12/12/1997
58	6,054,756	4/25/2000	DiStefano et al.	257	668	3/15/1999
59	6,063,648	5/16/2000	Beroz et al.	438	113	10/29/1998
60	6,064,213	5/16/2000	Khandros et al.	324	754	1/15/1997
61	6,075,289	6/13/2000	Distefano	257	732	11/4/1996
62	6,078,186	6/20/2000	Hembree et al.	324	755	12/31/1997
63	6,080,603	6/27/2000	Distefano et al.	438	117	3/15/1999
64	6,080,605	6/27/2000	Distefano et al.	438	126	10/6/1998
65	6,080,932	6/27/2000	Smith et al.	174	52.4	4/14/1998
66	6,081,035	6/27/2000	Warner et al.	257	773	10/24/1996


Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	67	WO 99/18445	15/04/1999	PCT	1	067		X

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	68	T. Tamura; <u>Probing Techniques for Ultra-High Pin Counts</u> ; NEC Research and Development; April 2000;
	69	E. Ehlermann; <u>Matched Expansion Probe Cards</u> ; Hiten 99 3 rd European Conference on High Temperature Electronics; 1999;
	70	T. Itoh, et al.; <u>Characteristics of Fritting Contacts Utilized for Micromachined Water Probe Cards</u> ; Review of Scientific Instruments; May 2000;
	71	Qing Tan, et al.; <u>Reliability Evaluation of Probe-Before-Bump Technology</u> ; 24 th IEEE/CPMT International Electronics Manufacturing Technology Symposium; 1999;
	72	I. Takahiro, et al.; <u>Fabrication of Micro IC Probe for LSI Testing</u> ; Sensors & Actuators A; March 10, 2000;
	73	K. Soejima, et al.; <u>New Probe Microstructure for Full-Water Contact-Probe Cards</u> ; 49 th Electronic Components & Technology Conference; 1999

10/06/9902



74	Ching-Lang Chiang; <u>Wafer Level Backside Emission Microscopy: Dynamics and Effects</u> ; Microelectronics Reliability; May 1999;
75	J.J. Broz, et al.; <u>Understanding Probe-Contact a-Spot Oxidation During Elevated-Temperature Wafer Test</u> ; Elevated Engineering; September 1999;
76	R. Pandey, et al.; <u>P4 Probe Card-A Solution for At-Speed, High Density, Wafer Probing</u> ; Proc. International Test Conference; 1998;
77	J. Anderson; <u>Integrated Probe card/Interface Solutions for Specific Test Applications</u> ; International Test Conference; 1998;
78	Yanwei Zhang, et al.; <u>Thermally Actuated Microprobes for a New Wafer Probe Card</u> ; Journal of Microelectromechanical Systems; March 1999;
79	R. Schwartz; <u>Measurement Repeatability Key to Probe-Card Metrology</u> ; EE-Evaluation Engineering; September 1998;
80	R.D. Bates, et al.; <u>Search for the Universal Probe Card Solution</u> ; International Test Conference; 1997;
81	J. Anderson; <u>High-Performance Multi-DUT Interfacing for Wafer Sort</u> ; September 1997;
82	Y. Zhang, et al.; <u>New MEMS Wafer Probe Card</u> ; Systems. An Investigation of Micro Structures, Sensors, Actuators, Machines and Robots; 1997;
83	S. Sasho, et al.; <u>Four Multi Probing Test for 16 Bit DAC with vertical contact Probe Card</u> ; 1996;
84	S. Asai, et al.; <u>Probe Card with Probe Pins Grown by the Vapor-Liquid-Solid (VLS) Method</u> ; IEEE Trans. On Components, Packaging, & Manufacturing Technology; June 1996;
85	J. Leung, et al.; <u>Active Substrate Membrane Probe Card</u> ; International Electron Devices Meeting Technical Digest; 1995;
86	M. Beiley, et al.; <u>Micromachined Array Probe Card-Characterization</u> ; IEEE Transactions on Components, Packaging, and Manufacturing Technology; February 1995;
87	M. Beiley, et al.; <u>A Micromachined Array Probe Card-Fabrication Process</u> ; IEEE Transactions on Components, Packaging, and Manufacturing Technology; February 1995;
88	M. Beiley et al.; <u>Micro-Machined Array Probe Card</u> ; Procedure of the IEEE International Electronics Devices Meeting; 1992;
89	E. Subramanian, et al.; <u>Enhanced Probe Card Facilities At-Speed Wafer Probing in Very High Density Applications</u> ; Procedure of International Test Conference; 1992;
90	M. Beiley, et al.; <u>Array Probe Card</u> ; Proceedings of the IEEE Multi-Chip Module Conference; 1992;
91	D.L. Landis; <u>Test Methodology for Wafer Scale System</u> ; IEEE Transactions on Computer-Aided Design of Integrated Circuits & Systems; January 1992;
92	T. Tada, et al.; <u>Fine Pitch Probe Technology for VLSI Wafer Testing</u> ; Procedure of International Test Conference; 1990;
93	S. Schleifer; <u>Improving Wafer Sort Yields with Radius-Tip Probes</u> ; Procedure of International Test Conference; 1990;
94	S. Hong, et al.; <u>Design & Fabrication of a Monolithic High-Density Probe Card for High-Frequency On-Wafer Testing</u> ; International Electronic Devices Meeting Technical Digest; 1989;
95	D.L. Landis; <u>Self-Test Methodology for Restructurable WSI</u> ; Procedure of the International Conference on Wafer Scale Integration; 1990;



10069902

96	J. Reagan, et al.; <u>Thin Film Hybrid Technology for On-Water Probing of Integrated Circuits</u> ; Hybrid Circuit Technology; April 1990;
97	Farid Matta; <u>Advances in IC Testing: The Membrane Probe Card</u> ; Hewlett-Packard Journal; June 1990;
98	David L. Landis; <u>A Self-Test System Architecture for Reconfigurable WSI</u> ; International Test Conference Procedure Meeting the Tests of Time; 1989;
99	Normand Nadeau and Sylvie Perreault; <u>An Analysis of Tungsten Probes' Effect on Yield in a Production Wafer Probe Environment</u> ; International Test Conference Procedure Meeting the Tests of Time; 1989;
100	Normand Nadeau, et al.; <u>Effect of Tungsten Probes on Wafer-Probe Yield in a Production Environment</u> ; Microelectronic Manufacturing & Testing; September 1989;
101	Mike Bonham, et al.; <u>Wafer-Probe Testing of High-Pin-Count ICs</u> ; Microelectronic Manufacturing and Testing; November 1988;
102	Brian Leslie, et al.; <u>Wafer-Level Testing with a Membrane Probe</u> ; IEEE Design & Test of Computers; February 1989;
103	C. Barsotti, et al.; <u>Very High Density Probing</u> ; International Test Conference Proceedings of the New Frontiers in Testing; 1988;
104	Brian Leslie, et al.; <u>Membrane Probe card Technology (The Future for High Performance Wafer test)</u> ; International Test Conference Procedures of the New Frontiers in Testing; 1988; and
105	C. Barsotti, et al.; <u>New Probe Cards Replace Needle Types</u> ; Semiconductor International; august 1988.

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.